6395578

## Semiconductor Package And Method For Fabricating The Same Inventor(s): SHIN et al. Application #: 09/574,541

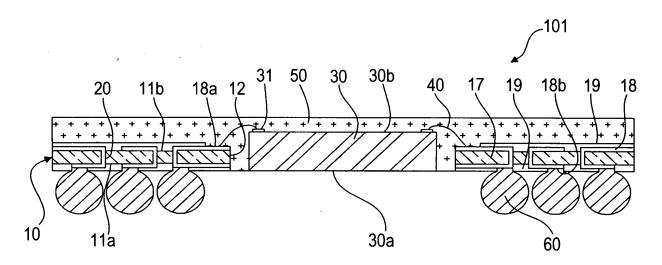


Fig.1

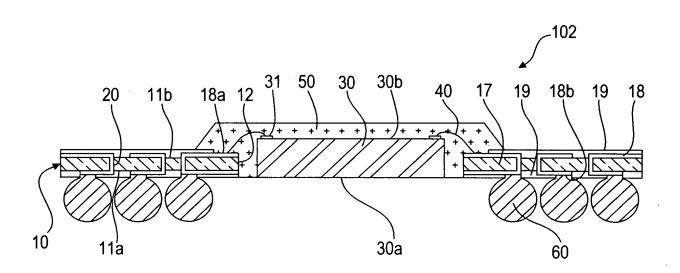


Fig. 2

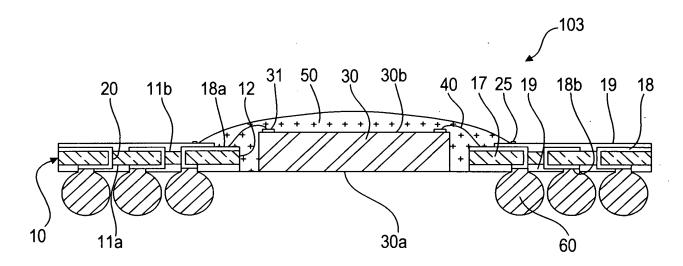


Fig.3

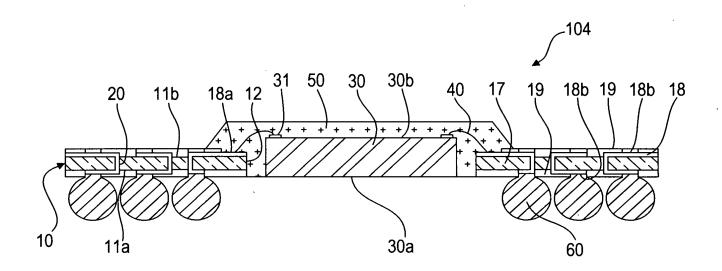


Fig. 4

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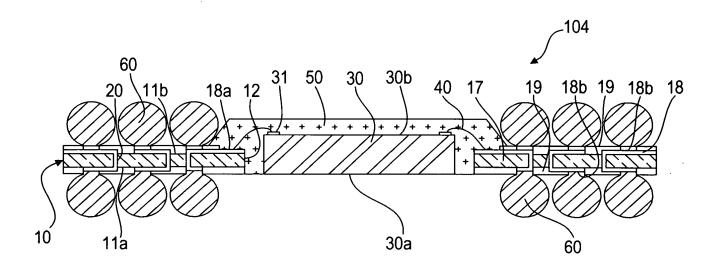
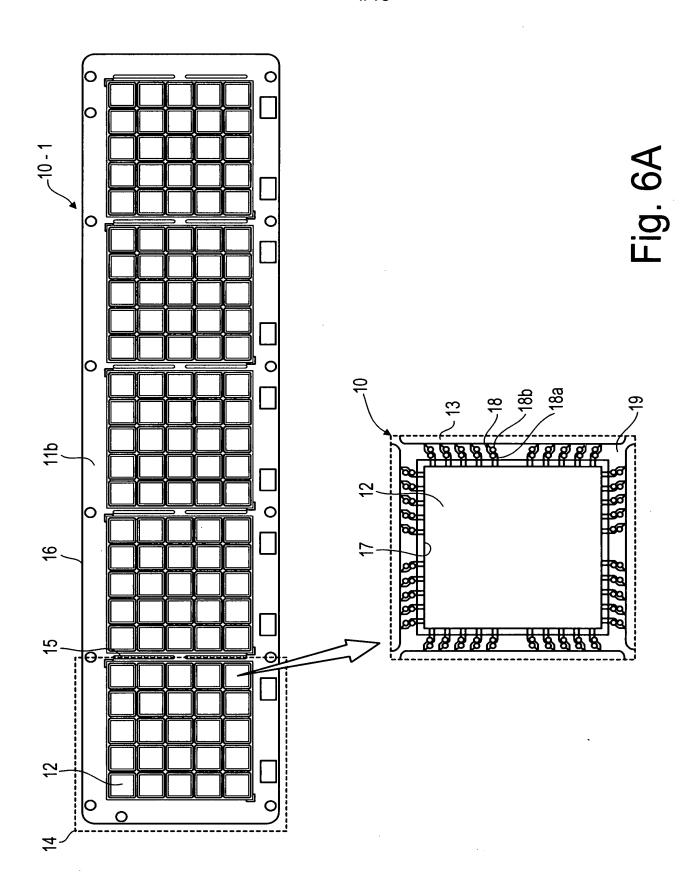
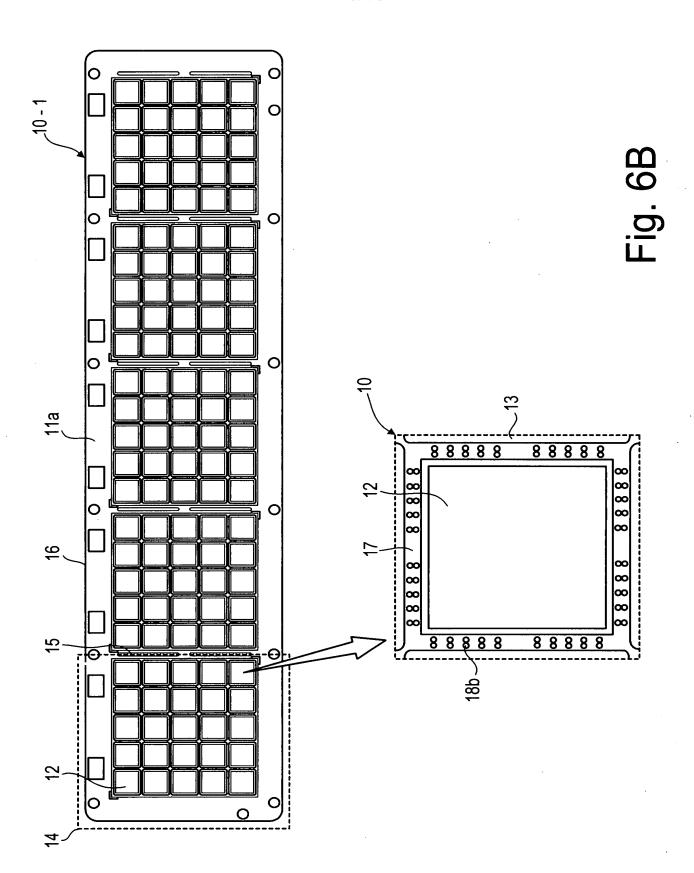


Fig. 5



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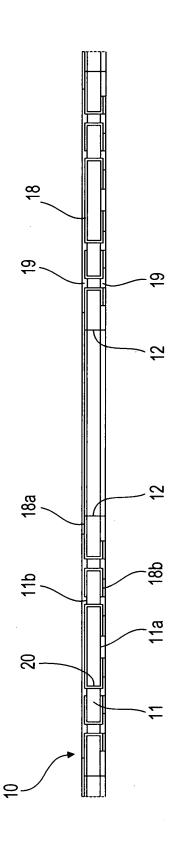


Fig. 7A

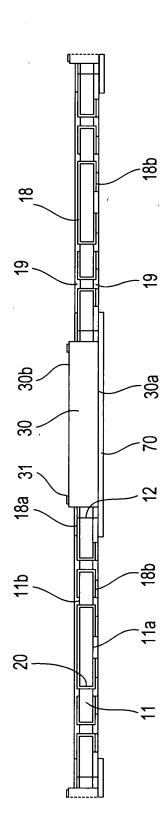
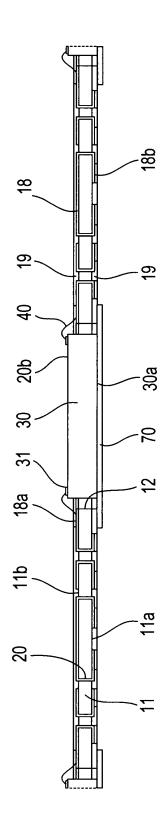
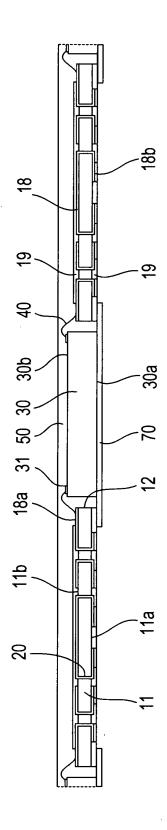
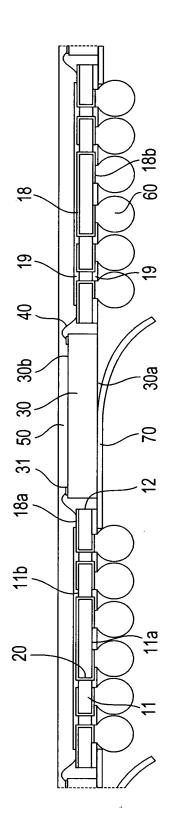
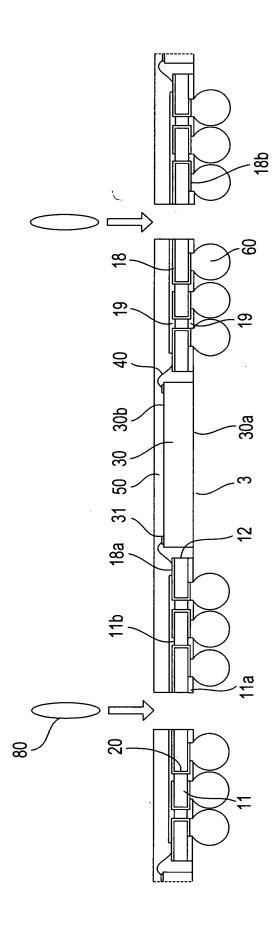


Fig. 7B









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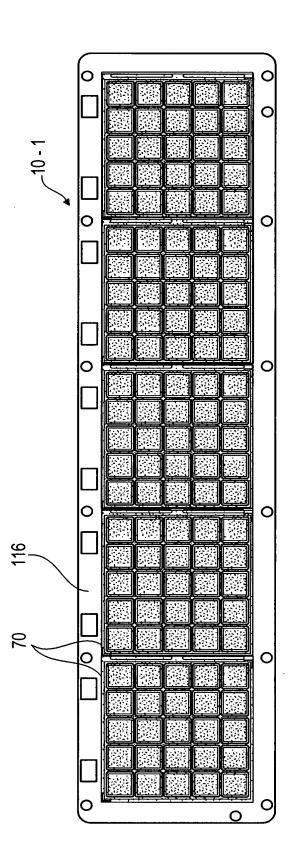


Fig. 8A

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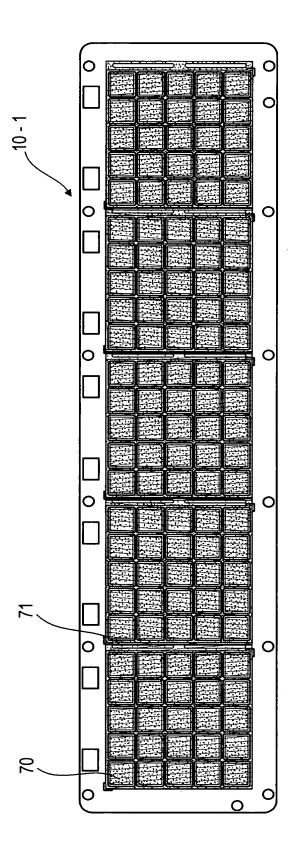


Fig. 8B

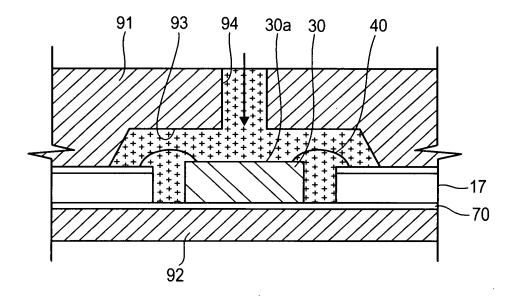


Fig. 9

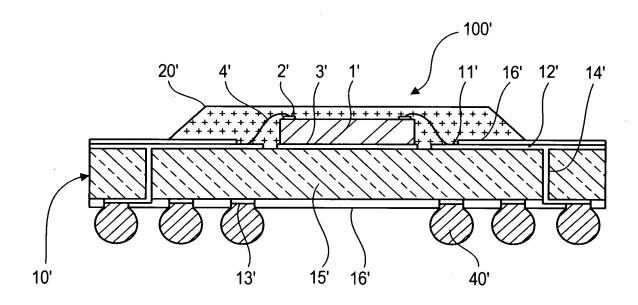


Fig. 10 (PRIOR ART)